

FIG. 1A

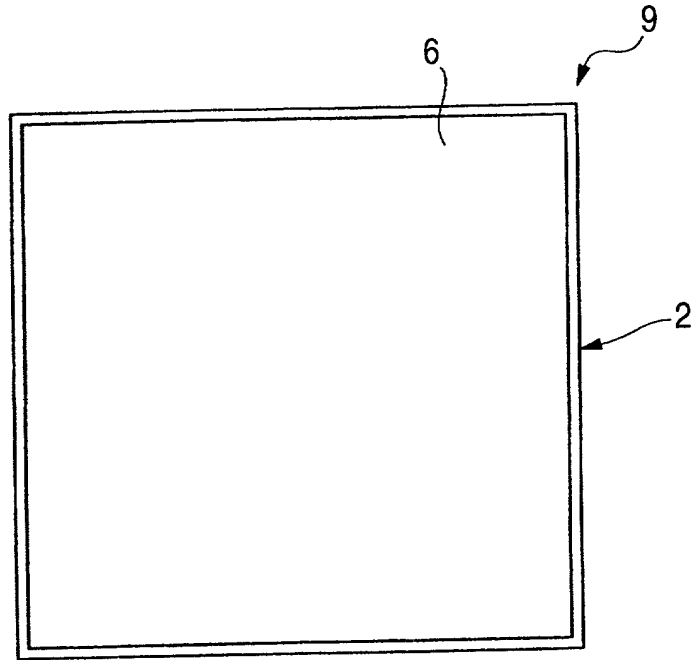
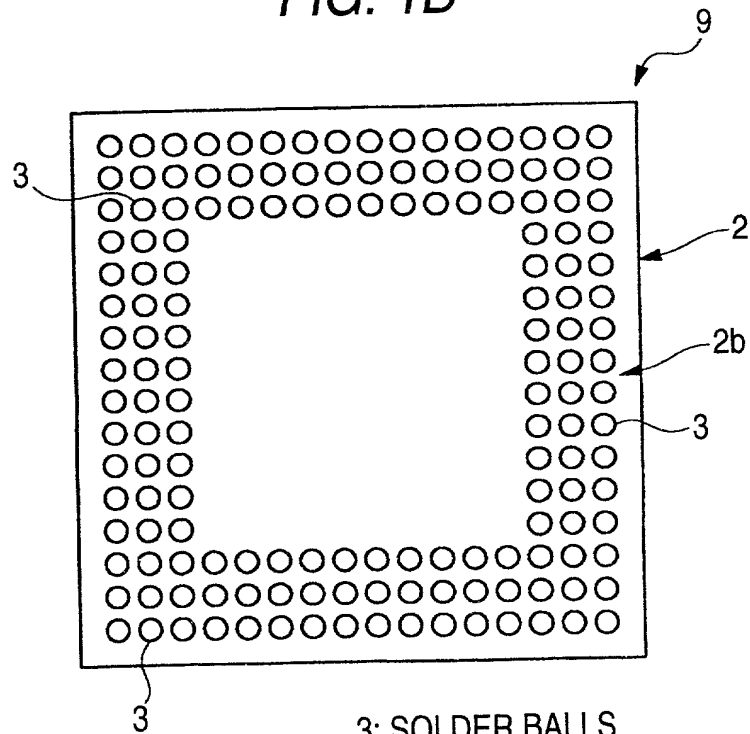
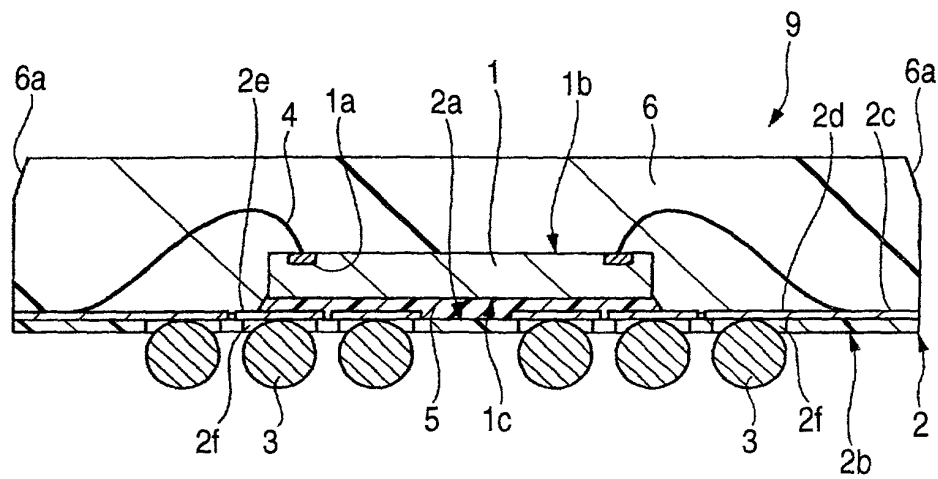


FIG. 1B



3: SOLDER BALLS
 6: SEALED PORTION
 9: CSP (SEMICONDUCTOR DEVICE)

FIG. 2



1a: PADS (SURFACE ELECTRODES)
 2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

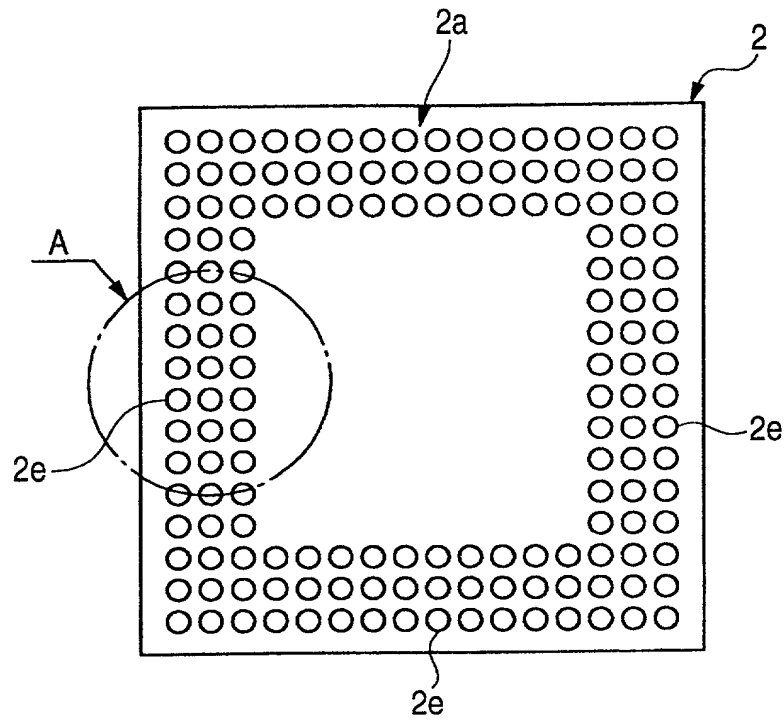


FIG. 3B

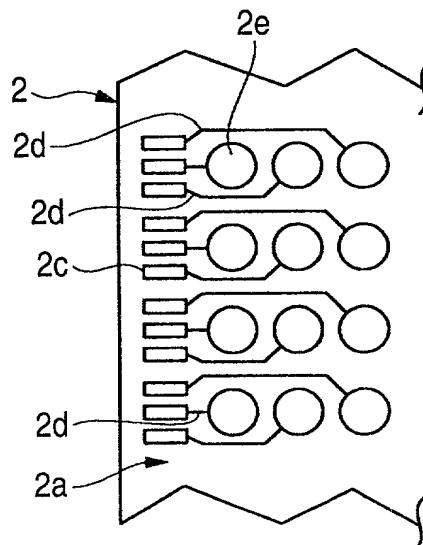
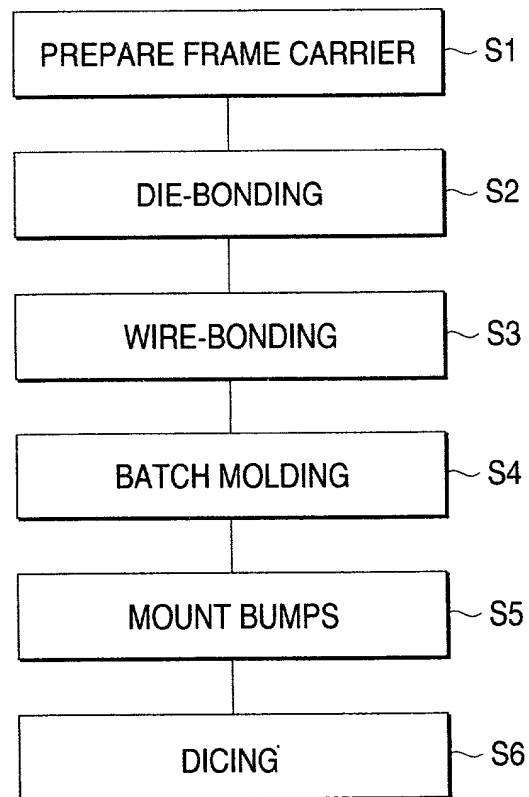


FIG. 4



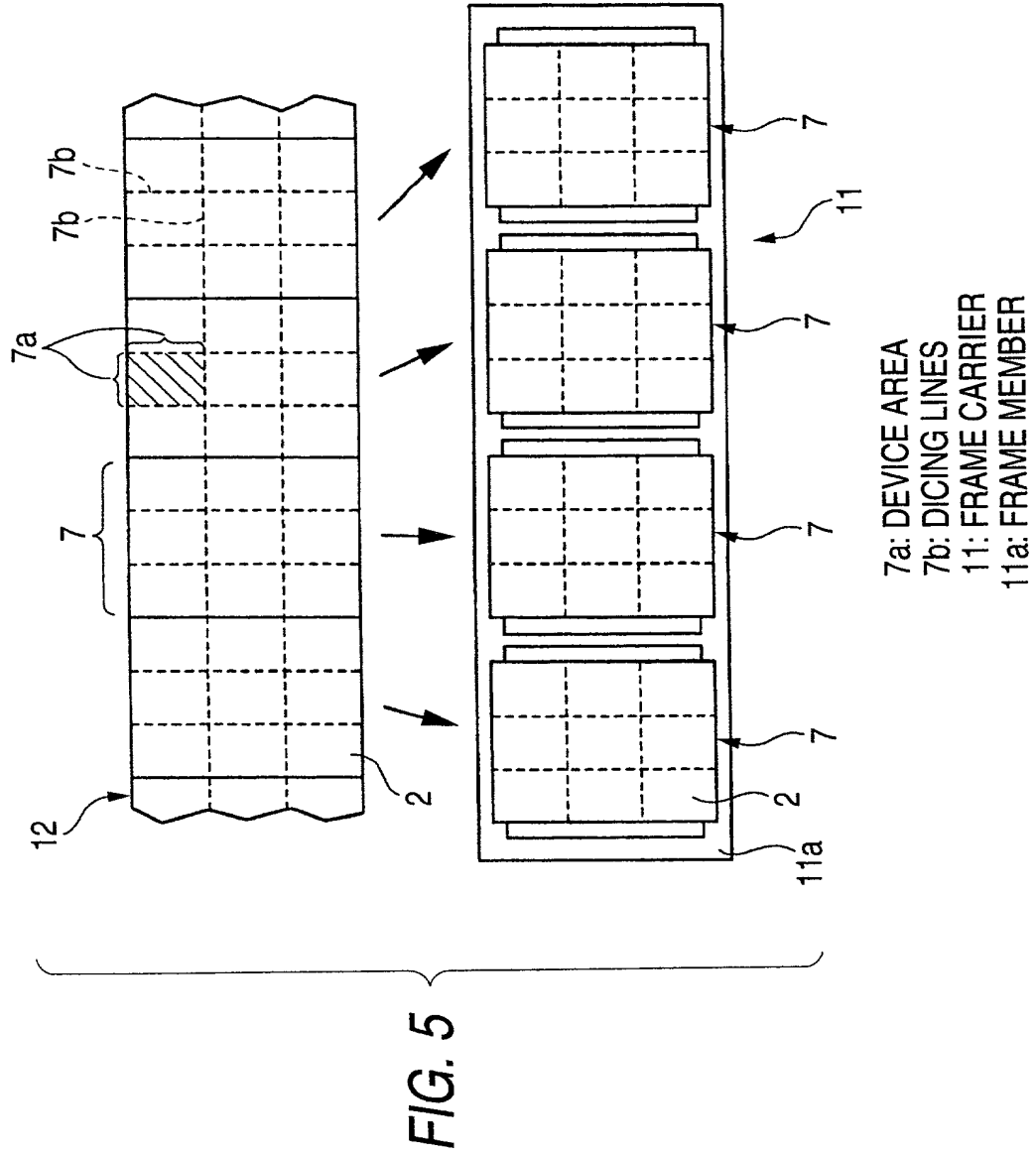


FIG. 6

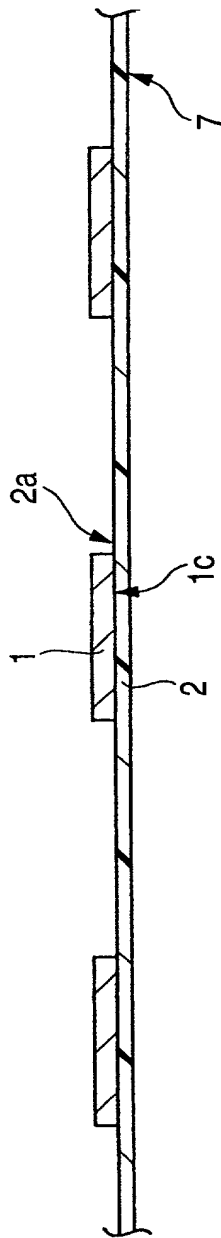
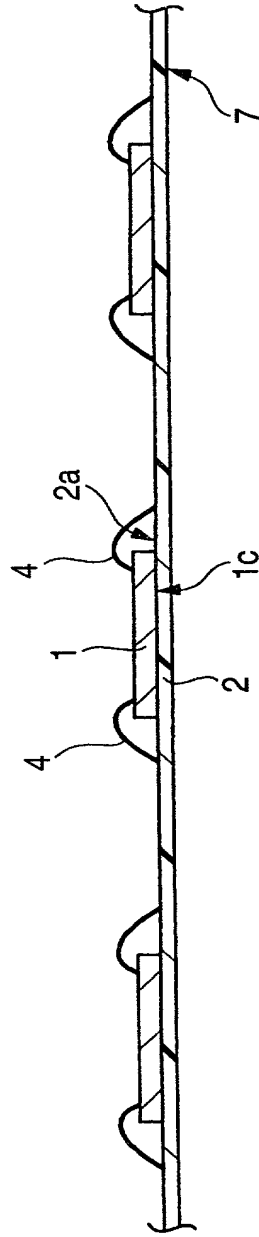


FIG. 7



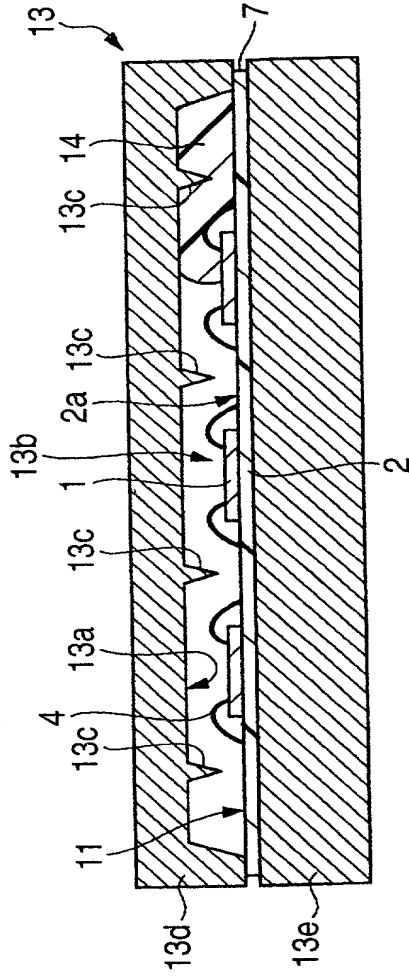
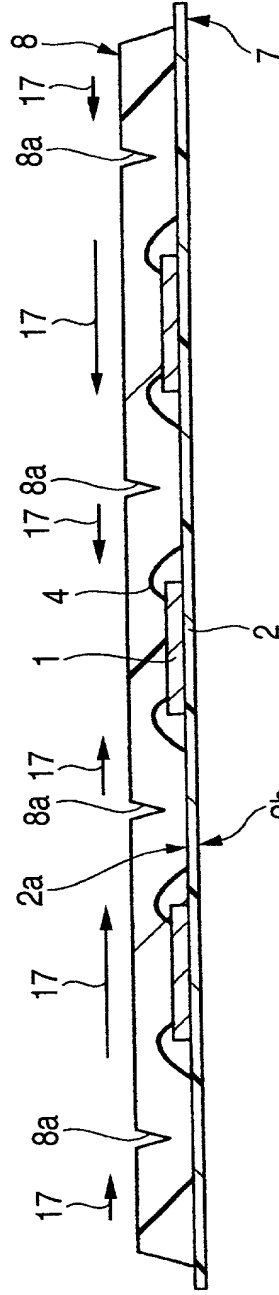


FIG. 8A

FIG. 8B



- 1: SEMICONDUCTOR CHIP
- 2: TAPE SUBSTRATE
(CHIP SUPPORTING SUBSTRATE)
- 2a: CHIP SUPPORTING FACE
- 2b: BACK FACE (OPPOSITE FACE)
- 4: WIRES (CONDUCTIVE MEMBERS)
- 7: MULTI-DEVICE SUBSTRATE
- 8: BLOCK-MOLDED PORTION
(BATCH-SEALED PORTION)
- 8a: GROOVES
- 13: MOLDING TOOL
- 13a: CAVITY FORMING FACE
- 13b: CAVITY
- 13c: PROTRUSIONS
- 14: MOLDING RESIN

FIG. 9

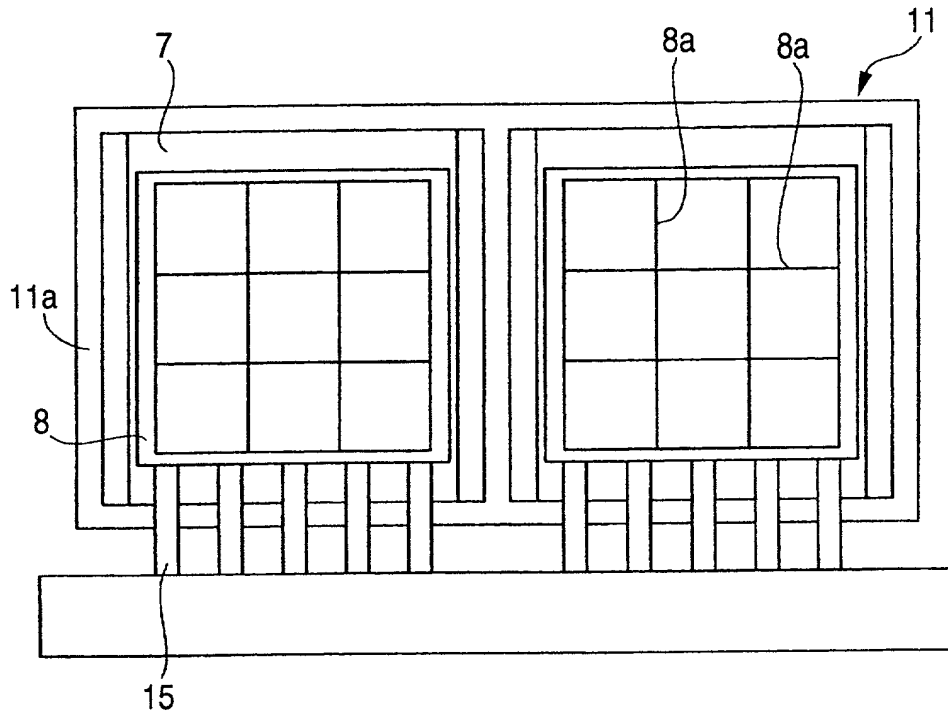
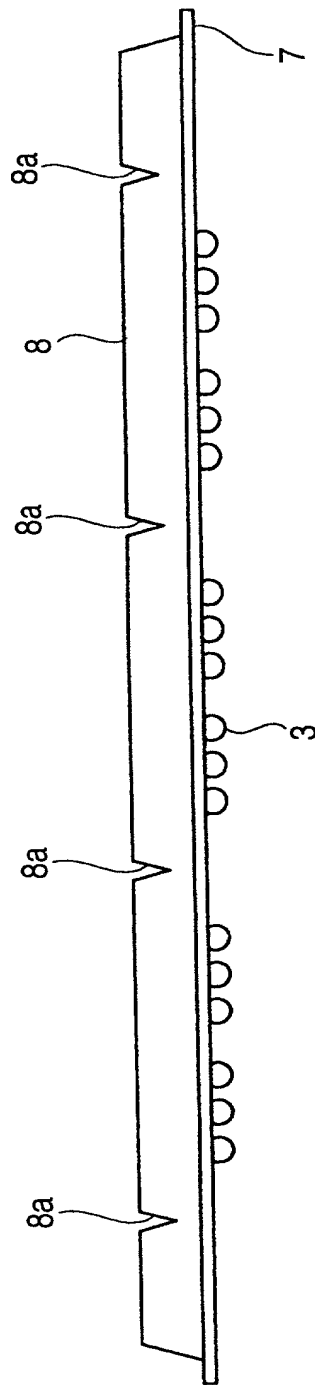


FIG. 9

FIG. 10



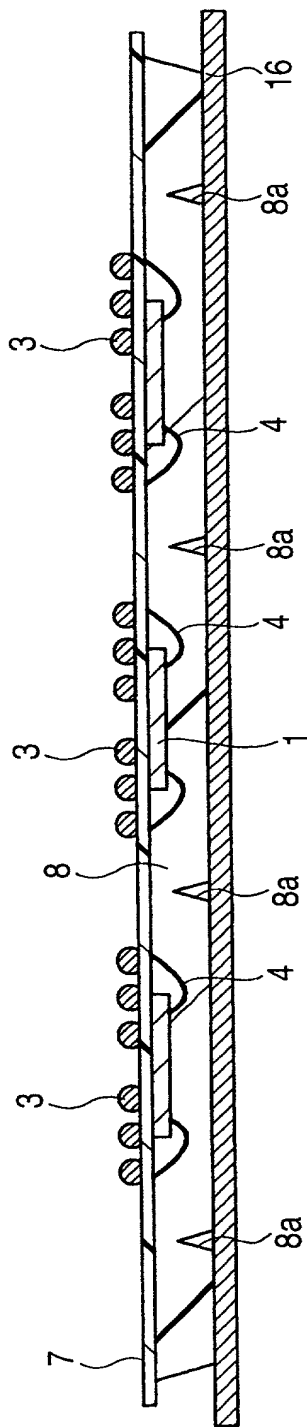
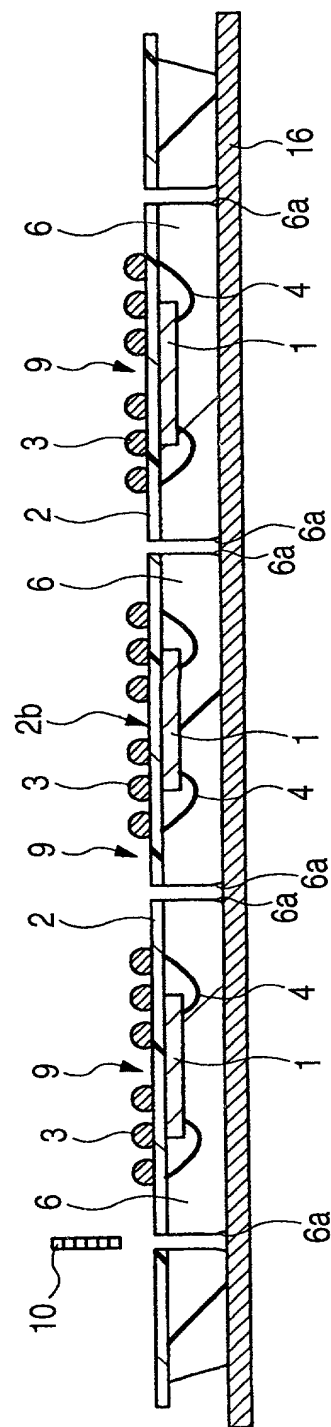


FIG. 11B



10: BLADE

FIG. 12

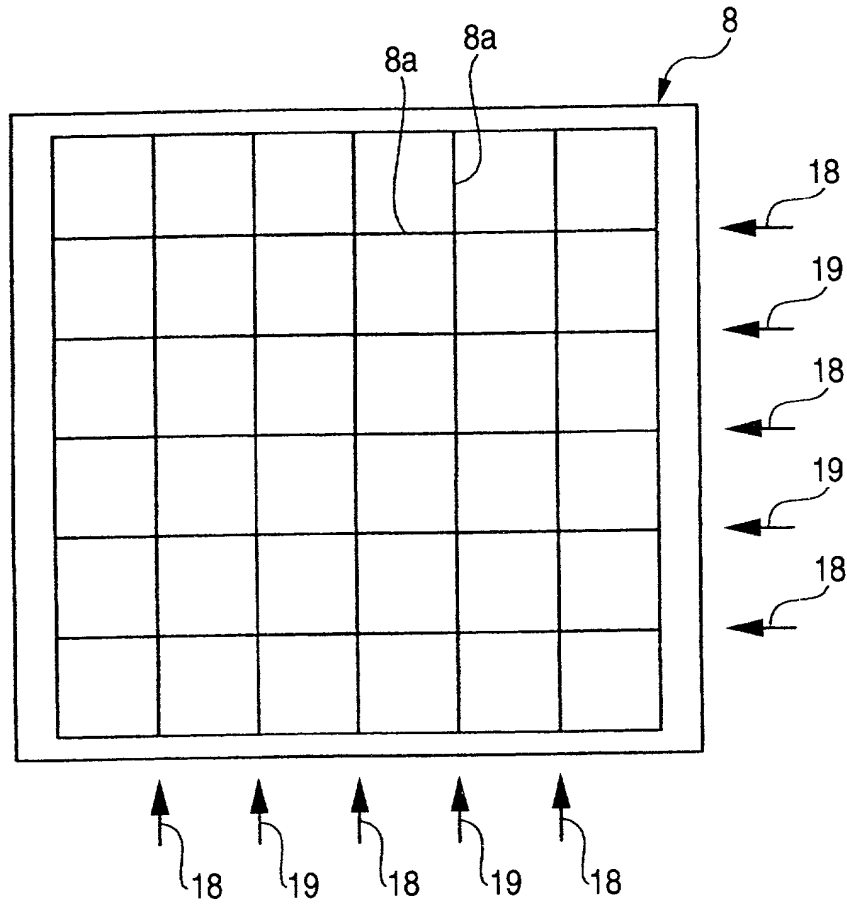


FIG. 13

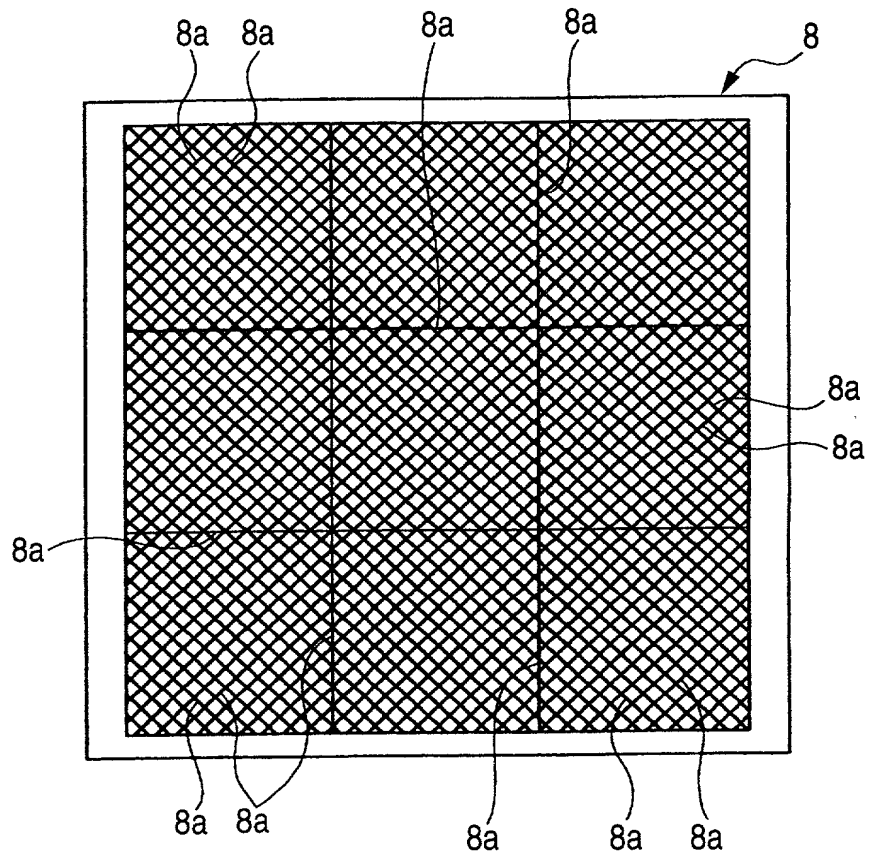


FIG. 13

FIG. 14

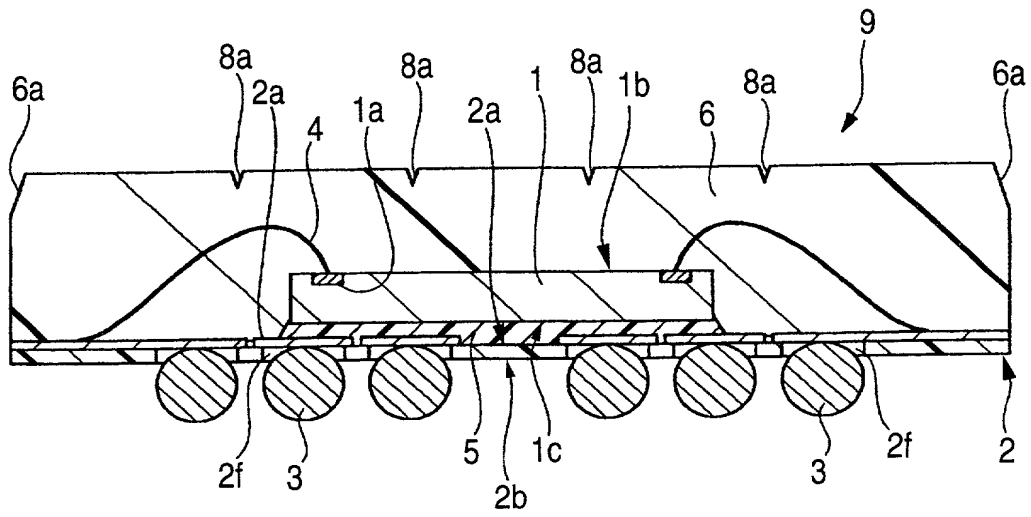


FIG. 15

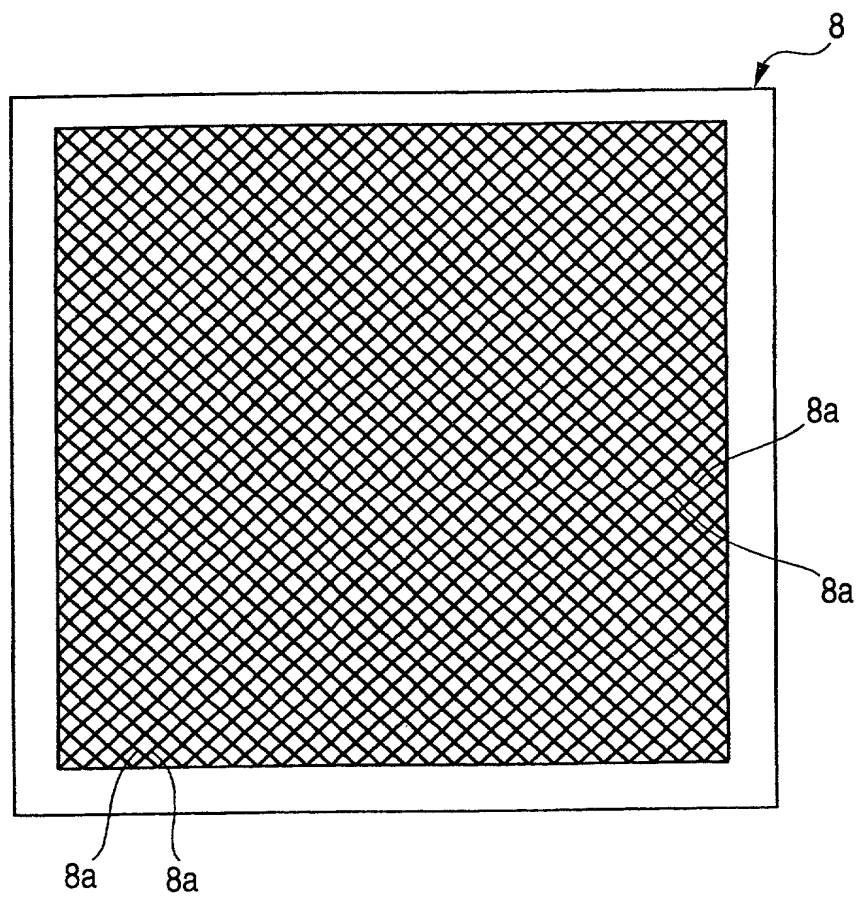


FIG. 16

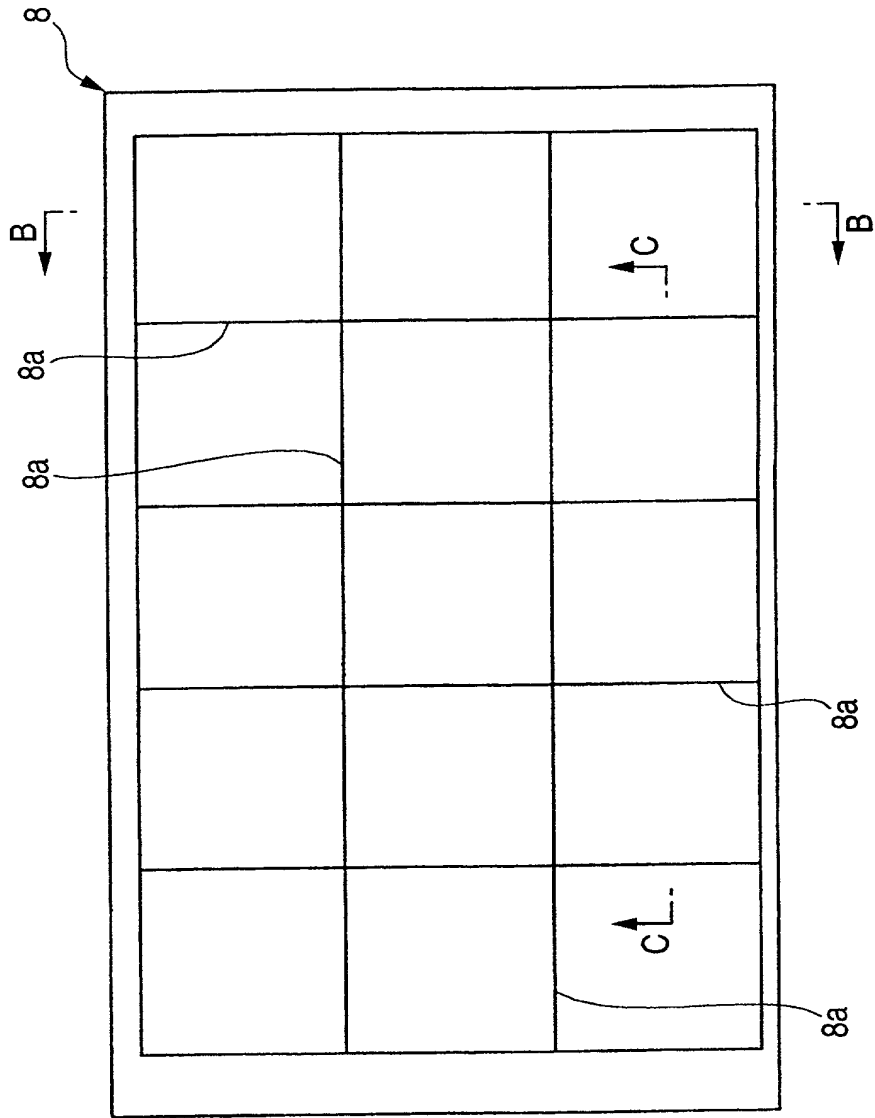


FIG. 17A

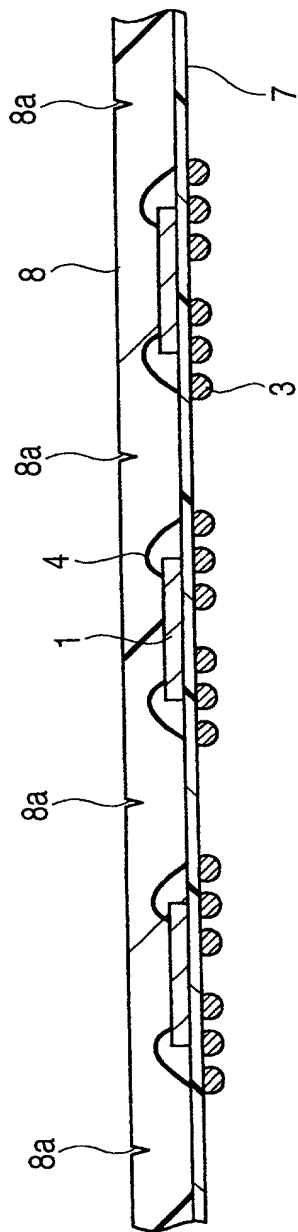


FIG. 17B

